

13th Gen Intel® Core™ Embedded Mobile Processors

conga-TC370



- ❖ 8th Generation Intel® Core™ SOC processor
- ❖ Up to 4 cores at low-power TDP of 15W
- ❖ New Intel® Gen 9 HD Graphics
- ❖ Optional eMMC 5.1 on board mass storage
- ❖ COM Express Compact Type 6 module 95x95 mm²

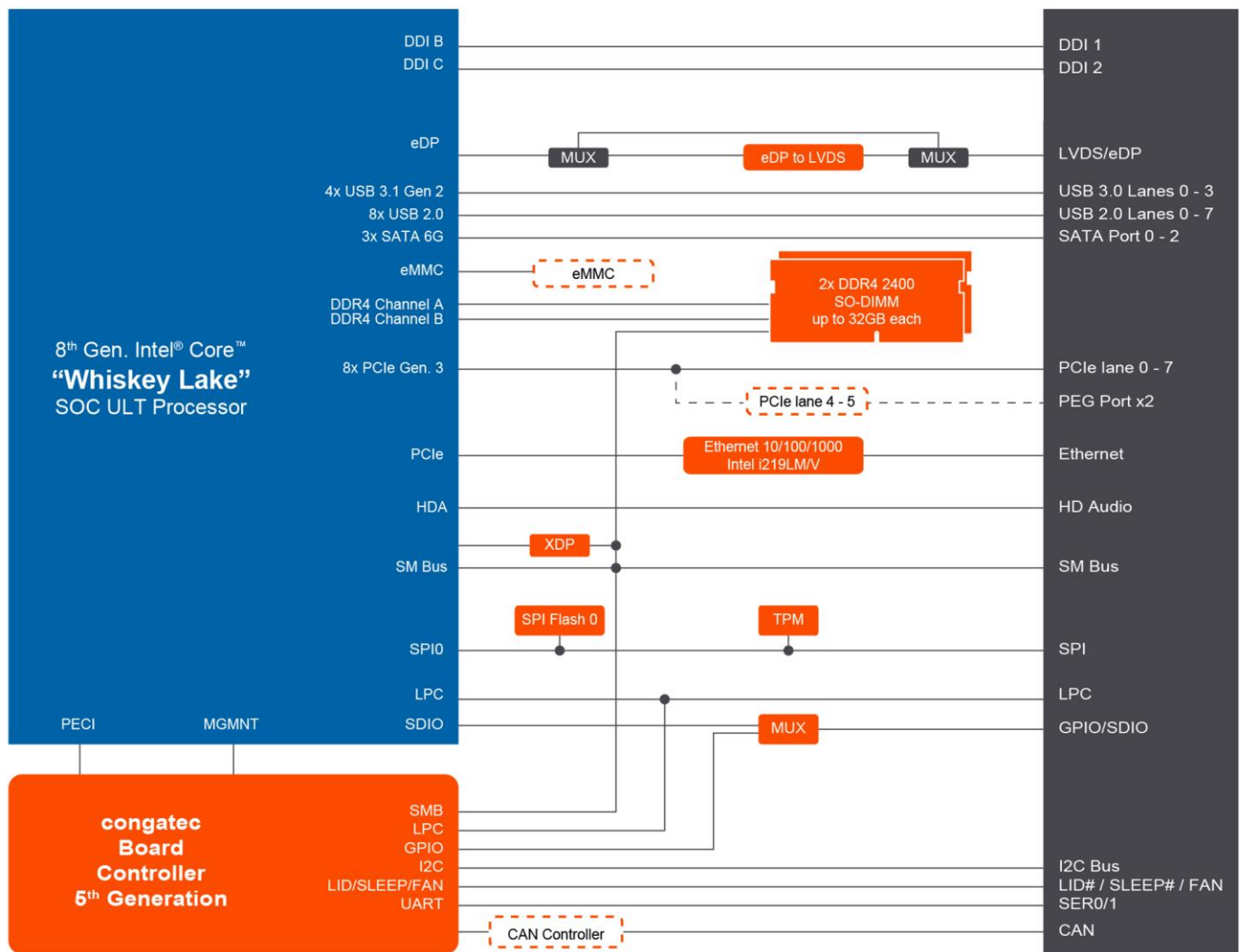
COM  **Express®**

Form factor

COM Express® Rev. 3.0, Compact form factor (95 x 95 mm), Type 6 Connector Pinout

CPU	Intel® Core™ i7-8665UE Intel® Core™ i5-8365UE Intel® Core™ i3-8145UE Intel® Celeron™ 4305UE	4 Cores 8 Threads 4 Cores 8 Threads 2 Cores 4 Threads 2 Cores 2 Threads	1.7 GHz 4.4 GHz (boost) 1.6 GHz 4.1 GHz (boost) 2.2 GHz 3.9 GHz (boost) 2.0 GHz	8 MB cache 6 MB cache 4 MB cache 2 MB cache	15-25 W cTDP 15-25 W cTDP 15-25 W cTDP 15 W TDP
DRAM	Dual channel DDR4 up to 2400 MT/s 2x SO-DIMM connector up to 2x 32 GByte RAM				
Chipset	Integrated in SoC				
Ethernet	Intel® i219-LM/V GbE LAN controller with AMT 12.0 support				
I/O Interfaces	8x PCI Express™ Gen 3.0 lanes 3x SATA Gen 3 4x USB 3.1 Gen 2 @ 10 Gbit/s 8x USB 2.0 LPC bus I²C bus (fast mode, 400 kHz, multi-master) 2x UART				
Sound	Digital High-Definition Audio Interface with support for multiple audio codecs				
Graphics	Intel® Gen9 HD Graphics Engine with OpenCL 2.1, OpenGL 4.5 and DirectX 11/12 up to three independent displays: HDMI 2.0a / DisplayPort 1.2 / eDP 1.4 / (VGA optional) MPEG-2 , WMV9 (VC-1), H.265 decoding HEVC, VP9 encoding				
Storage	optional eMMC 5.1 on board mass storage				
congatec Board Controller	Multi-Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics I²C bus (fast mode, 400 kHz, multi-master) Power Loss Control Hardware Health Monitoring POST Code redirection				
Embedded BIOS Features	AMI Aptio® UEFI 2.x firmware 32 MByte serial SPI firmware flash				
Security	TPM 2.0 Infineon SLB9670				
Power Management	ACPI compliant with battery support Suspend to RAM (S3) support S5 enhanced support Intel AMT 12.0 support				
Operating Systems	Microsoft® Windows 10 (64bit only) Microsoft® Windows 10 IoT Enterprise (64bit only) Linux				
Power Consumption	See user's guide for full details				
Temperature	Operating: 0 to +60°C		Storage: -20 to +80°C		
Extended Temperature	Screening service on request:		-25 to +80°C (burn-in & cold-soak) -40 to +85°C (burn-in & cold-soak)		
Humidity	Operation 10% to 85% r. H. non cond.		Storage 5% to 85% r. H. non cond.		
Size	95 x 95 mm (3.74" x 3.74")				

conga-TC370 | Block Diagram



 Optional - Not available by default

conga-TC370 | Order Information

Article	PN	Description
conga-TC370/i7-8665UE	048800	COM Express Type 6 Compact module based on Intel® Core™ i7-8665UE 4-core processor with 1.7GHz up to 4.4GHz turbo boost, 8MB L2 cache, Intel® UHD Graphics 620 and dual channel DDR4 2400 MT/s memory interface (formerly Whiskey Lake).
conga-TC370/i5-8365UE	048801	COM Express Type 6 Compact module based on Intel® Core™ i5-8365UE 4-core processor with 1.6GHz up to 4.1GHz turbo boost, 6MB L2 cache, Intel® UHD Graphics 620 and dual channel DDR4 2400 MT/s memory interface (formerly Whiskey Lake).
conga-TC370/i3-8145UE	048802	COM Express Type 6 Compact module based on Intel® Core™ i3-8145UE 2-core processor with 2.2GHz up to 3.9GHz turbo boost, 4MB L2 cache, Intel® UHD Graphics 620 and dual channel DDR4 2400 MT/s memory interface (formerly Whiskey Lake).
conga-TC370/4305UE	048804	COM Express Type 6 Compact module based on Intel® Celeron™ 4305UE 2-core processor with 2.0GHz, 2MB L2 cache, Intel® UHD Graphics 610 and dual channel DDR4 2133 MT/s memory interface (formerly Whiskey Lake).
conga-TC370/CSA-HP-B	048850	Standard active cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes, 25.5mm overall cooling height and integrated 12V fan. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-TC370/CSA-HP-T	048851	Standard active cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes, 25.5mm overall cooling height and integrated 12V fan. Threaded mounting with threaded standoffs M2.5.
conga-TC370/CSP-HP-B	048852	Standard passive cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes and 24.3mm overall cooling height. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-TC370/CSP-HP-T	048853	Standard passive cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes and 24.3mm overall cooling height. Threaded mounting with threaded standoffs M2.5.
conga-TC370/HSP-HP-B	048854	Standard heatspreader for COM Express Compact modules conga-TC370 with integrated heat pipes and 11mm overall cooling height. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-TC370/HSP-HP-T	048855	Standard heatspreader for COM Express Compact modules conga-TC370 with integrated heat pipes and 11mm overall cooling height. Threaded mounting with threaded standoffs M2.5.
DDR4-SODIMM-2400 (4GB)	068790	DDR4 SODIMM memory module with 2400 MT/s and 4GB RAM
DDR4-SODIMM-2400 (8GB)	068791	DDR4 SODIMM memory module with 2400 MT/s and 8GB RAM
DDR4-SODIMM-2400 (16GB)	068792	DDR4 SODIMM memory module with 2400 MT/s and 16GB RAM
DDR4-SODIMM-2666 (32GB)	068806	DDR4 SODIMM memory module with 2666 MT/s and 32GB RAM
conga-TEVAL	065810	Evaluation carrier board for Type 6 COM-Express-modules